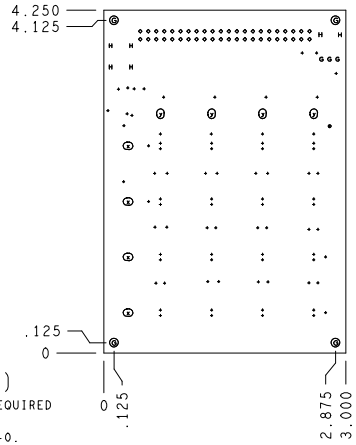
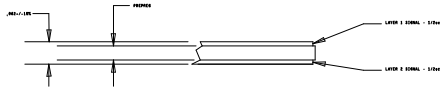
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	Initial Release	01/10/09	RKAD
02	Change in position of RT1 and R1, Updated Silk of J1 connector	02/14/09	RKAD
**	Released to Manufacturing	03/10/09	RKAD





DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	12.0	+3.0/-3.0	PLATED	80
•	20.0	+0.0/-0.0	PLATED	1
G	42.0	+3.0/-3.0	PLATED	3
H	43.0	+3.0/-3.0	PLATED	6
◇	43.0	+3.0/-3.0	PLATED	44
ⓖ	SLOT--> 120X90	+0.0/-0.0	NON-PLATED	4
ⓖ	SLOT--> 90X120	+0.0/-0.0	NON-PLATED	4
ⓒ	125.0	+2.0/-2.0	NON-PLATED	4

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE AND LOGO ON SECONDARY SIDE IN ETCH (PREFERRED) OR SILKSCREEN.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GURANTEED WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES TOLERANCES ON: ANGLES +/- 2 2 PL DECIMALS +/- .010 3 PL DECIMALS +/- .005 THIRD ANGLE PROJECTIONS	DRAWN	03/10/2009
	CHECKED	
	ENGRG	
	ISSUED	

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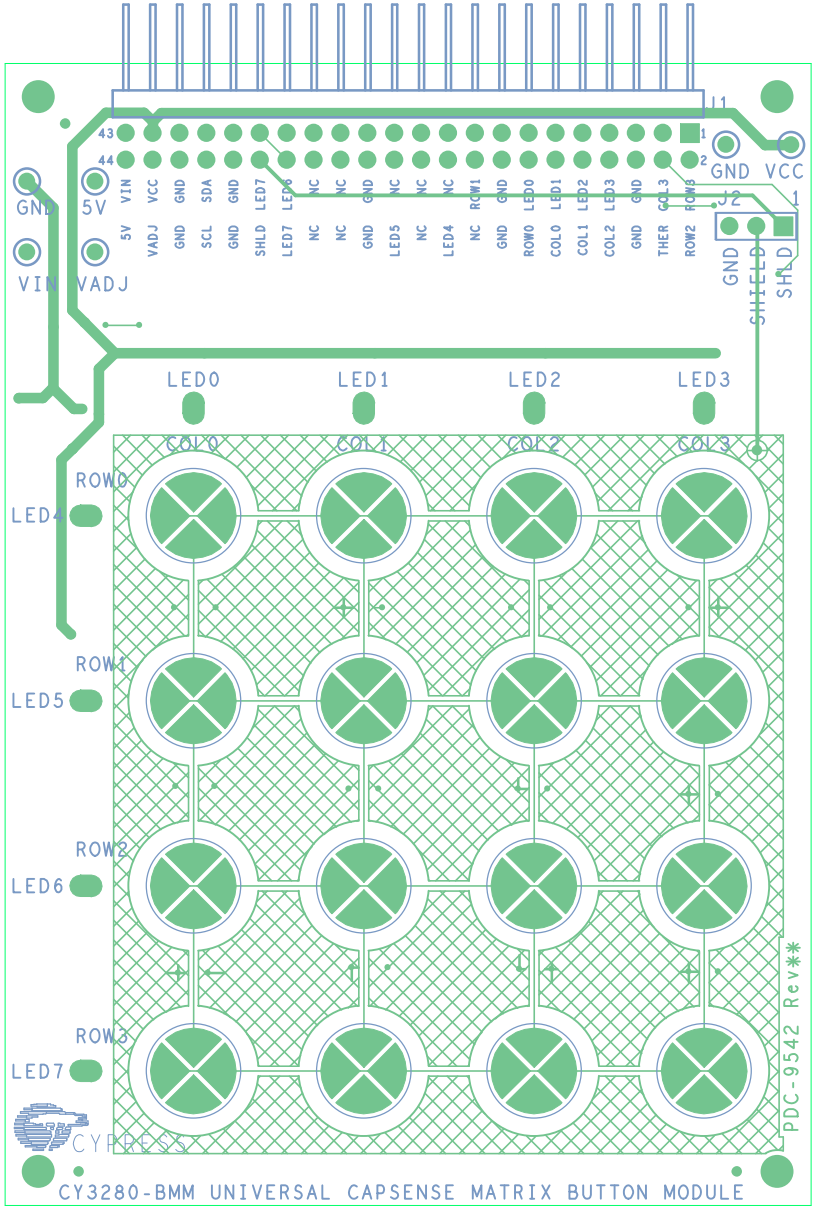
COMPANY : CYPRESS SEMICONDUCTOR

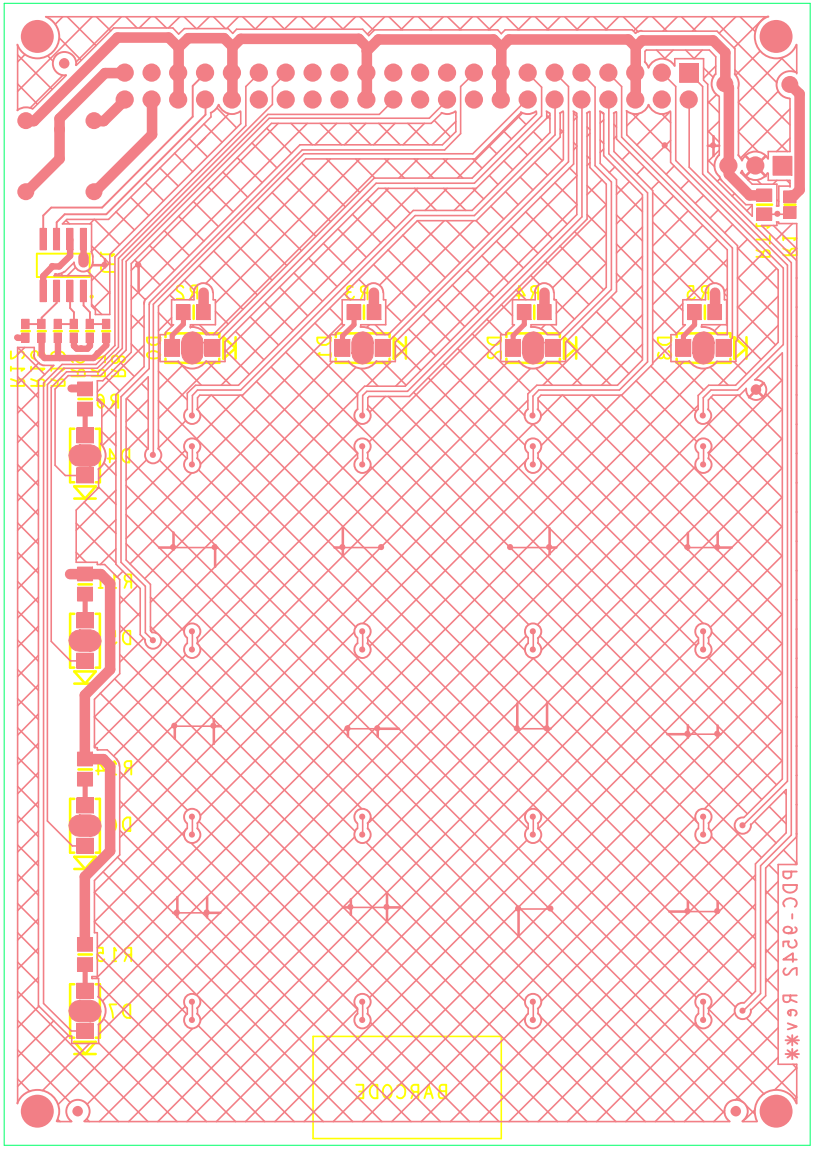
FABRICATION DRAWING CY3280 - MATRIX BUTTON MODULE

SIZE	FSCM NO	DWG NO	REV
C		CY3280-BMM	**

SCALE:1/1 SHEET: 1 OF 2



CY3280-BMM REV ** PRIMARY SILKSCREEN



CY3280-BMM REV ** SECONDARY SILKSCREEN